

CPH3406-TL-E-VB Datasheet N-Channel 60-V (D-S) MOSFET

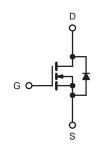
PRODUC	T SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
60	0.075 at V _{GS} = 10 V	4.0	2.1 nC
00	0.086 at V _{GS} = 4.5 V	3.8	2.1110

FEATURES

- Halogen-free According to IEC 61249-2-21
 Available
- Trench Power MOSFET
- 100 % Rg Tested
- 100 % UIS Tested

APPLICATIONS

- Battery Switch
- DC/DC Converter



G 1 (SOT23) S 2 Top View

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A =	25 °C, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	60	V
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		4.0	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C	I-	3.4	
Continuous Drain Current $(1) = 150^{\circ}$ C)	T _A = 25 °C	I _D	3.1 ^{b, c}	
	T _A = 70 °C		2.5 ^{b, c}	Α
Pulsed Drain Current	·	I _{DM}	12	A
Continuous Source-Drain Diode Current	T _C = 25 °C	°C	1.39	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.91 ^{b, c}	
Avalanche Current	L = 0.1 mH	I _{AS}	6	
Single-Pulse Avalanche Energy	_	E _{AS}	1.8	mJ
	T _C = 25 °C		1.66	
Movimum Douver Dissinction	T _C = 70 °C	Б	1.06	W
Maximum Power Dissipation	T _A = 25 °C	P _D	1.09 ^{b, c}	vv
	T _A = 70 °C	_	0.7 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	C/W

Notes:

a. Based on $T_C = 25 \text{ °C}$.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under Steady State conditions is 120 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = 250 \mu A$	60			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 A		55		m)//80
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		3	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current	1	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	8			Α
		V _{GS} = 10 V, I _D = 1.9 A		0.075		_
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 1.7 A		0.086		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15V, I _D = 1.9 A		5		S
Dynamic ^b	<u> </u>				•	1
Input Capacitance	C _{iss}			180		
Output Capacitance	C _{oss}			22		
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		13		pF
		$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 1.9 \text{ A}$		4.2	6.1	
Total Gate Charge	Qg			2.1	3.2	
Gate-Source Charge	Q _{gs}	Q_{gs} V _{DS} = 30 V, V _{GS} = 4.5 V, I _D = 1.9 A		0.7		nC
Gate-Drain Charge	Q _{gd}			1		
Gate Resistance	R _g	f = 1 MHz	0.6	2.2	5.1	Ω
Turn-On Delay Time	t _{d(on)}			4	6	
Rise Time	tr	V_{DD} = 30 V, R_{L} = 20 Ω		10	15	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.5 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_G = 1 \Omega$		10	15	ns
Fall Time	t _f			7	10.5	
Turn-On Delay Time	t _{d(on)}			15	23	
Rise Time	t _r	V_{DD} = 30 V, R_L = 20 Ω		16	24	
Turn-Off Delay Time	t _{d(off)}	$I_D = 1.5 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{G}} = 1 \Omega$		11	17	ns
Fall Time	t _f			11	17	
Drain-Source Body Diode Characteristic	s				•	1
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			2.19	٨
Pulse Diode Forward Current ^a	I _{SM}				7	
Body Diode Voltage	V _{SD}	I _S = 1.5 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			15	23	ns
Body Diode Reverse Recovery Charge	Q _{rr}			10	15	nC
Reverse Recovery Fall Time	ta	$I_F = 1.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{T}_J = 25 ^\circ\text{C}$		12		
Reverse Recovery Rise Time	t _b			3		ns

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



2.8

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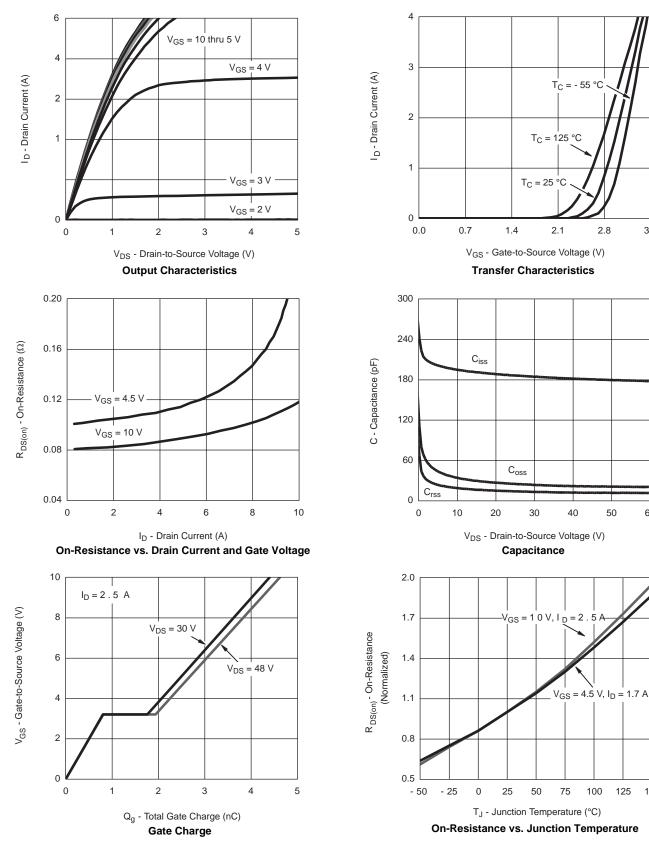
100

125 150

60

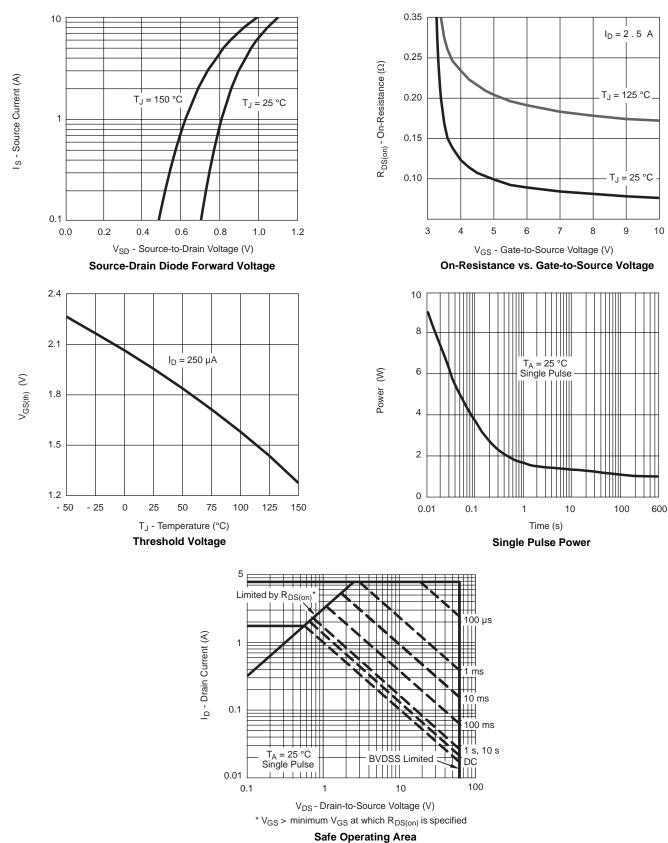
3.5





服务热线:400-655-8788

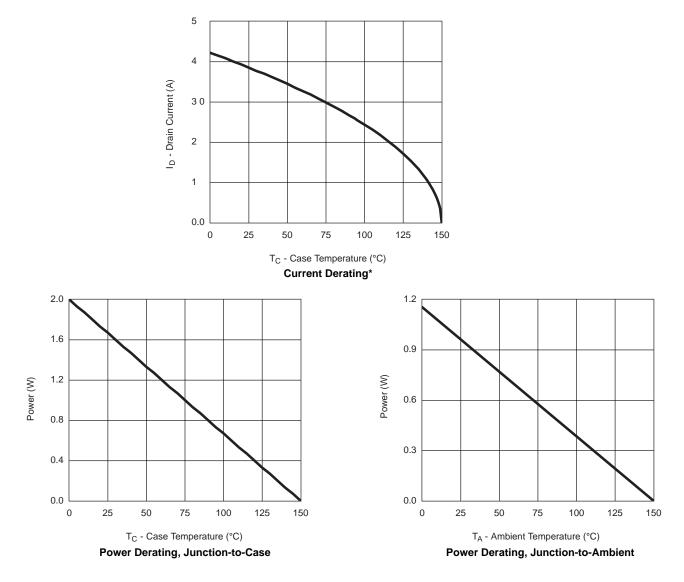




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

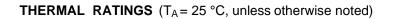


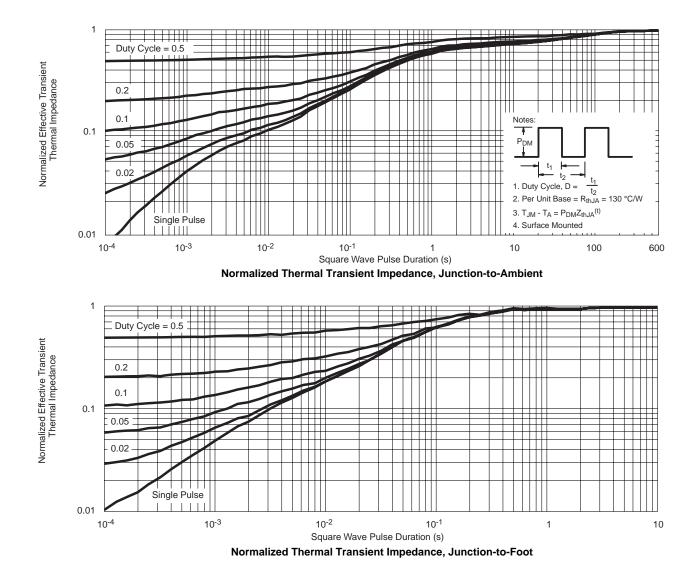
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* The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.









SOT-23 (TO-236): 3-LEAD







Max 1.12 0.10 1.02 0.50 0.18 3.04 2.64 1.40	Min 0.035 0.0004 0.0346 0.014 0.003 0.110 0.083	Max 0.044 0.004 0.040 0.020 0.007 0.120 0.104	
0.10 1.02 0.50 0.18 3.04 2.64	0.0004 0.0346 0.014 0.003 0.110 0.083	0.004 0.040 0.020 0.007 0.120	
1.02 0.50 0.18 3.04 2.64	0.0346 0.014 0.003 0.110 0.083	0.040 0.020 0.007 0.120	
0.50 0.18 3.04 2.64	0.014 0.003 0.110 0.083	0.020 0.007 0.120	
0.18 3.04 2.64	0.003 0.110 0.083	0.007 0.120	
3.04 2.64	0.110 0.083	0.120	
2.64	0.083		
		0.104	
1 40			
1.40	0.047	0.055	
BSC	0.0374	1 Ref	
BSC	0.0748 Ref		
0.60	0.016	0.024	
Ref	0.025	Ref	
Ref	0.020	Ref	
8°	3°	8°	
	4 Ref D Ref 8°	0.020 Ref 0.020	



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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